

In the Abstract:

Please replace the Abstract with the following amended Abstract:

The invention relates to a cooling structure of an electronic equipment needing forced air cooling by fans and so forth and has an object to enhance a cooling capacity and enhance a mounting efficiency of the substrate units. The A cooling structure of an electronic equipment needing forced air cooling comprises, to achieve the above object, includes substrate housing parts, an upstream side duct, a downstream side duct, an exhaust device means and an air adjusting means part. The substrate housing parts detachably house therein one or plurality of substrate units, and the downstream side duct allows the cooling air for cooling, which passed from the upstream side duct through the substrate housing part, to flow. The exhaust means device is provided at the an exhaust part to forcibly discharge air to the outside air, thereby allowing the cooling air for cooling to flow to the substrate housing parts, and the The air adjusting means part adjusts the volume for cooling air for cooling which flows to the downstream side duct.